

High Performance High Flow Rate Fully Cured Dispensable Gel

THERMA-A-GAP GEL 60HF is part of the Parker Chomerics family of fully cured, one component, silicone-based, dispensable thermal interface materials. With a 6.2 W/m-K thermal conductivity, it is designed for high performance heat transfer from electronics components to cooling features and meant to be used across industries and applications. The “HF” in GEL 60HF stands for “High Flow”, indicating that the material is ideal for high volume dispensing applications and high throughput production operations. As with all Parker Chomerics thermal gels, it is optimized for automated dispensing at various packaging sizes while retaining properties for easy rework and field repair situations. The paste-like consistency of THERMA-A-GAP GEL 60HF enables tightly controlled dispensing and accurate material placement during assembly. It requires low compressive force to deflect under assembly pressure, subjecting components, solder joints and PCB leads to minimal stress.

PRODUCT FEATURES:

- Thermal conductivity: 6.2 W/m-K
- High flow rate: 80g/min
- No secondary curing required
- Low thermal impedance
- Very low compression force
- Reworkable
- Single component
- Room temperature storage



IDEAL APPLICATIONS:

- Consumer electronics
- Telecommunications equipment
- Energy storage devices
- Power electronics and modules
- Automotive control units and sensors
- Computing components (CPUs, GPUs, memory)

Authorized Canadian Partner



MATRIX PRECISION CONVERTING

Your Application. Our Expertise.

Matrix specializes in precision cutting and converting of engineered materials to meet the exact specifications required by manufacturers. Our state-of-the-art equipment and expertise ensure precise customization, providing manufacturers with streamlined solutions to enhance their product quality and performance.

	Typical Properties†	GEL 60HF	Test Methods
Physical	Color	Grey/Black	Visual
	Flow Rate, g/min - 30cc syringe with no tip, 0.100" orifice, 90psi (621 kPa)	80	Chomerics
	Specific Gravity	3.3	ASTM D792
	Typical Minimum Bondline Thickness, in (mm)	0.006 (0.15)	Chomerics
Thermal	Thermal Conductivity, W/m-K	6.2	ASTM D5470
	Heat Capacity, J/g-K	1	ASTM E1269
	Coefficient of Thermal Expansion, ppm/K	150	ASTM E831
	Operating Temperature Range, °F (°C)	-67 to 392 °F (-55 to 200 °C)	Chomerics
Electrical	Dielectric Strength, Vac/mil (kVac/mm)	125 (5.0)	ASTM D149
	Volume Resistivity, ohm-cm	10 ¹³	ASTM D257
	Dielectric Constant @ 1000 kHz at 0.020" (0.50mm) thick	5.8 / 4.8	ASTM D150
	Dissipation Factor @ 1000 kHz at 0.020" (0.50mm) thick	0.001/0.002	Chomerics
Regulatory	Flammability Rating (See UL File E482354 for Details)	V-0	UL 94
	RoHS Compliant	Yes	Chomerics Certification
	Outgassing, % TML (% CVCM)	0.14 (0.07)	ASTM E595
	Shelf Life, months from date of manufacture	12	Chomerics
	Storage Conditions, °F (°C) @ 50% Relative Humidity	50 to 90 (10 to 32)	Chomerics